

Appl. No. 10/708,705
Amdt. dated February 22, 2005
Reply to Office action of December 15, 2004

Amendments to the Claims:

This listing of claims will replace all prior versions and listings of claims in the application:

Listing of Claims:

- 1 (currently amended): A wire bonding package comprising:
- 5 a housing having a plurality of pins installed;
a circuit board installed inside the housing, the circuit board comprising at least a
trace connected to the pins of the housing;
at least a die installed on the circuit board, the die having a plurality of bonding pads
installed; and
- 10 at least a first bonding line connected between the bonding pads of the die and the
trace of the circuit board so that the bonding pads of the die are electrically
connected to the pins of the housing; and
at least one solder pad soldered to the first bonding line at a point on the first
bonding line between the bonding pad of the die and the trace of the circuit
15 board for separating the first bonding line from other bonding lines.
- 2 (original): The wire bonding package of claim 1, wherein the housing comprises a
lead frame for accommodating the circuit board.
- 20 3 (original): The wire bonding package of claim 1 comprising a plurality of die stacked
on the circuit board.
- 4 (original): The wire bonding package of claim 1 comprising a plurality of die, at least
two of the die adhering to the circuit board.
- 25 5 (original): The wire bonding package of claim 1, wherein the housing is a ball grid
array (BGA).

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6 (original): The wire bonding package of claim 1, wherein the housing is a quad flat package (QFP).

5 7 (original): The wire bonding package of claim 1, wherein the housing is a dual in-line package (DIP).

8 (original): The wire bonding package of claim 1 further comprising at least a passive component installed on the circuit board.

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9 (new): The wire bonding package of claim 1 wherein the solder pad is located on the circuit board for soldering the first bonding line to the circuit board.

10 (new): A wire bonding package comprising:

15 a housing having a plurality of pins installed;
a circuit board installed inside the housing, the circuit board comprising at least a trace connected to the pins of the housing;
at least a die installed on the circuit board, the die having a plurality of bonding pads installed;
20 at least a first bonding line connected between the bonding pads of the die and the trace of the circuit board so that the bonding pads of the die are electrically connected to the pins of the housing; and
a first via and a second via formed in the circuit board, the first bonding line passing through the first and second vias such that a section of the first bonding line
25 between the first and second vias is located beneath the circuit board.

11 (new): The wire bonding package of claim 10, wherein the housing comprises a lead frame for accommodating the circuit board.

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12 (new): The wire bonding package of claim 10 comprising a plurality of die stacked on the circuit board.

5 13 (new): The wire bonding package of claim 10 comprising a plurality of die, at least two of the die adhering to the circuit board.

14 (new): The wire bonding package of claim 10, wherein the housing is a ball grid array (BGA).

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15 (new): The wire bonding package of claim 10, wherein the housing is a quad flat package (QFP).

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16 (new): The wire bonding package of claim 10, wherein the housing is a dual in-line package (DIP).

17 (new): The wire bonding package of claim 10 further comprising at least a passive component installed on the circuit board.

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